

CLAIMS:

1. A printhead assembly comprising:
an elongated beam formed from odd number of layers, there being a pair of outer layers symmetrically disposed about and laminated to a core, the coefficient of thermal expansion of the core and the outer layers providing a coefficient of expansion, in the beam,
5 substantially equal to that of silicon.
2. The support structure of claim 1, wherein:
the outer layers are the same thickness.
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3. The support structure of claim 1, wherein:
the outer layers are made from invar.
4. The support structure of claim 1, wherein:
15 the coefficient of thermal expansion of the outer layers and the core is different.
5. The support structure of claim 1, and further comprising:
a plurality of printhead modules positioned end to end along the beam.
- 20 6. The support structure of claim 5, wherein:
the printhead modules are all silicon MEMS type modules.
7. The support structure of claim 1, wherein:
the layers are hot rolled.
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8. The support structure of claim 7, wherein:
the layers are three in number and the core has a coefficient of thermal expansion
greater than that of silicon.
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